

# SMB1N-1650D

- Infrared High Power LED
- 1650 nm, 36 mW
- InGaAsP chip, 1000 x 1000 μm
- PA9T SMD package
- Beam Angle: ± 64°



### Description

**SMB1N-1650D** is a surface mount InGaAsP based high power infrared LED, with a typical peak wavelength of 1650 nm and optical output power of 36 mW @ 1 A. It comes in polyamide resin SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and silicone resin molded flat window

### Maximum Ratings\*

Devementer	Cumbal	Va	l lmit		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	PD		3300	mW	
Forward Current	IF		1500	mA	
Pulse Forward Current **	IFP		4000	mA	
Reverse Voltage	UF		3	V	
Thermal Resistance	Rthja		10	K/W	
Junction Temperature	TJ		120	°C	
Operating Temperature	TCASE	- 40	+ 85	°C	
Storage Temperature	T <sub>STG</sub>	- 40	+ 100	°C	
Lead Solder Temperature (t <sub>max</sub> . 5s)	T <sub>SLD</sub>		+ 250	°C	

\* Operating close to or exceeding these parameters may damage the device

\*\* duty cycle = 1 %, pulse width = 10  $\mu$ s

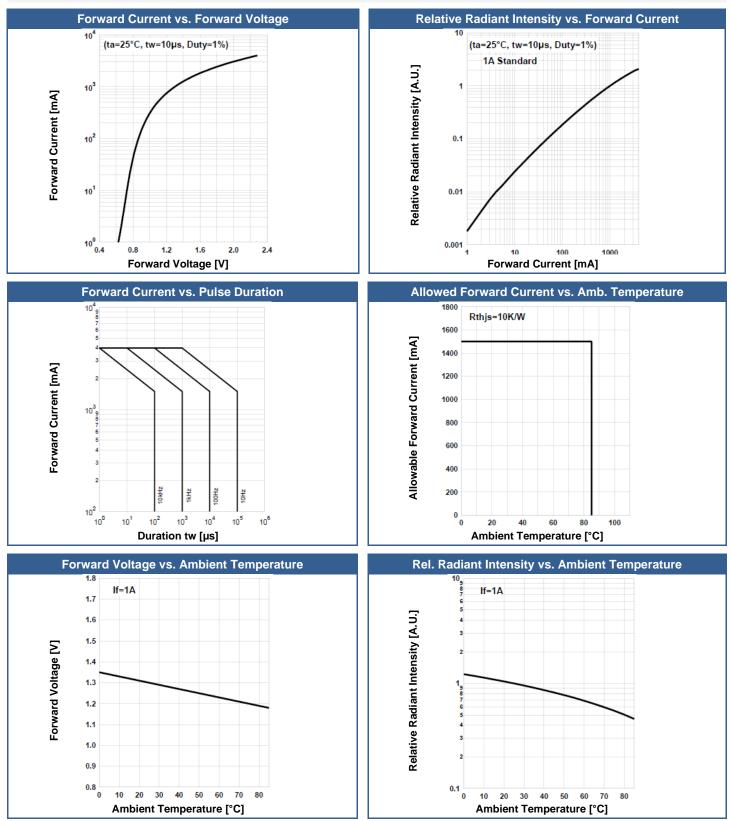
### Electro-Optical Characteristics (T<sub>CASE</sub> = 25°C)

Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λP	I⊧=1 A	1600		1700	nm
Half Width	$\lambda_{\Delta}$	IF=1 A		130		nm
Forward Voltage	VF	IF=1 A		1.3	1.6	V
	VFP	IFP=2 A*		1.7		
Total Radiated Power	Po	I <sub>F</sub> =1 A	16	36		mW
		I <sub>FP</sub> =2 A*		62		
Radiant Intensity	l <sub>E</sub>	IF=1 A		12		mW/sr
		I <sub>FP</sub> =2 A*		20		
Beam Angle	<b>20</b> 1/2	I <sub>F</sub> =100 mA		128		deg.
Rise Time	tr	IF=1 A		90		ns
Fall Time	<b>t</b> f	I <sub>F</sub> =1 A		30		ns

\* duty cycle = 1 %, pulse width = 10 µs

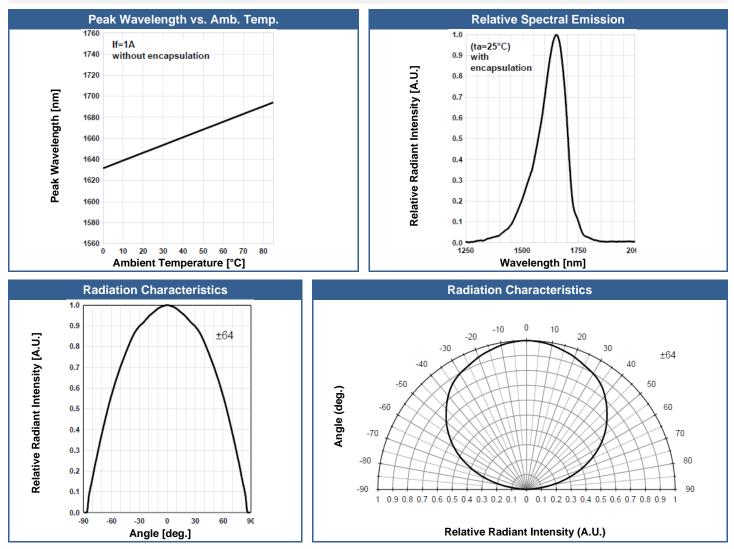


## **Typical Performance Curves**

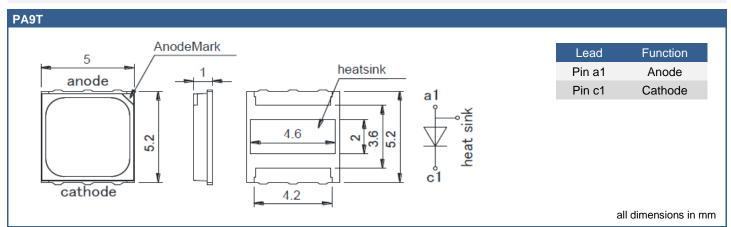




# **Typical Performance Curves**



### **Outline Dimensions**

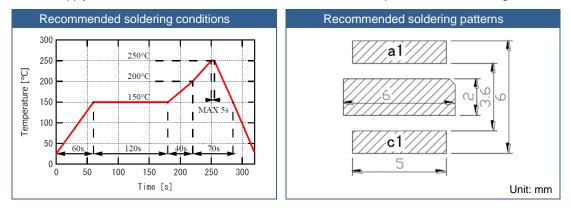




### **General Notes**

#### Soldering

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- · Do not apply current to the LED until it has cooled down to room temperature after soldering



#### Cleaning

- · Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended
- DO NOT USE acetone, chloroseen, trichloroethylene, or MKS
- DO NOT USE ultrasonic cleaners

#### Static Electricity

- LEDs are sensitive to electrostatic discharge (ESD).
- · Precautions against ESD must be taken when handling or operating these LEDs
- · Surge voltage or electrostatic discharge can result in complete failure of the LED.

#### Radiation

- During operation these LEDs do emit light, which could be hazardous to skin and eyes, and may cause cancer.
- Do avoid exposure to the emitted light. Protective glasses if needed
- It is further advised to attach a warning label on products/systems.

#### Operation

- Do only operate LEDs with a current source.
- Running these LEDs from a voltage source will result in complete failure of the device.
- Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

#### Storage

- The maximum shelf life of LEDs in the originally sealed aluminum bag is 12 months.
- Before opening the aluminum bag, please store it at <30 °C, <60 % RH.
- After opening the aluminum bag, please solder the LEDs within 72 hours (floor life) at 5 30 °C, <50 % RH.
- Put any unused, remaining LEDs and silica gel back in the same aluminum bag and then vacuum-seal the bag.
- It is recommended to keep the re-sealed bag in a desiccator at <30%RH.

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The above specifications are for reference purpose only and subjected to change without prior notice